

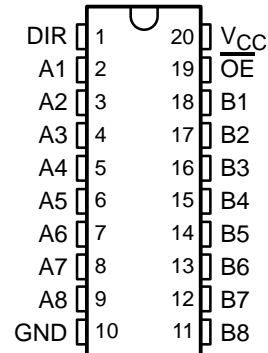
SN54LS245, SN74LS245 OCTAL BUS TRANSCEIVERS WITH 3-STATE OUTPUTS

SDLS146A – OCTOBER 1976 – REVISED FEBRUARY 2002

- 3-State Outputs Drive Bus Lines Directly
- PNP Inputs Reduce dc Loading on Bus Lines
- Hysteresis at Bus Inputs Improves Noise Margins
- Typical Propagation Delay Times Port to Port, 8 ns

TYPE	I _{OL} (SINK CURRENT)	I _{OH} (SOURCE CURRENT)
SN54LS245	12 mA	-12 mA
SN74LS245	24 mA	-15 mA

SN54LS245 . . . J OR W PACKAGE
SN74LS245 . . . DB, DW, N, OR NS PACKAGE
(TOP VIEW)

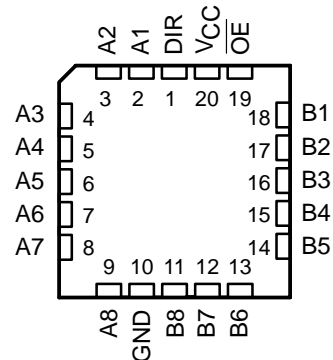


description

These octal bus transceivers are designed for asynchronous two-way communication between data buses. The control-function implementation minimizes external timing requirements.

The devices allow data transmission from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (DIR) input. The output-enable (\overline{OE}) input can disable the device so that the buses are effectively isolated.

SN54LS245 . . . FK PACKAGE
(TOP VIEW)



ORDERING INFORMATION

T _A	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
0°C to 70°C	PDIP – N	Tube	SN74LS245N	SN74LS245N
	SOIC – DW	Tube	SN74LS245DW	LS245
		Tape and reel	SN74LS245DWR	
	SOP – NS	Tape and reel	SN74LS245NSR	74LS245
SSOP – DB	Tape and reel	SN74LS245DBR	LS245	
-55°C to 125°C	CDIP – J	Tube	SN54LS245J	SN54LS245J
		Tube	SNJ54LS245J	SNJ54LS245J
	CFP – W	Tube	SNJ54LS245W	SNJ54LS245W
	LCCC – FK	Tube	SN54LS245FK	SN54LS245FK

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

 **TEXAS
INSTRUMENTS**

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On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

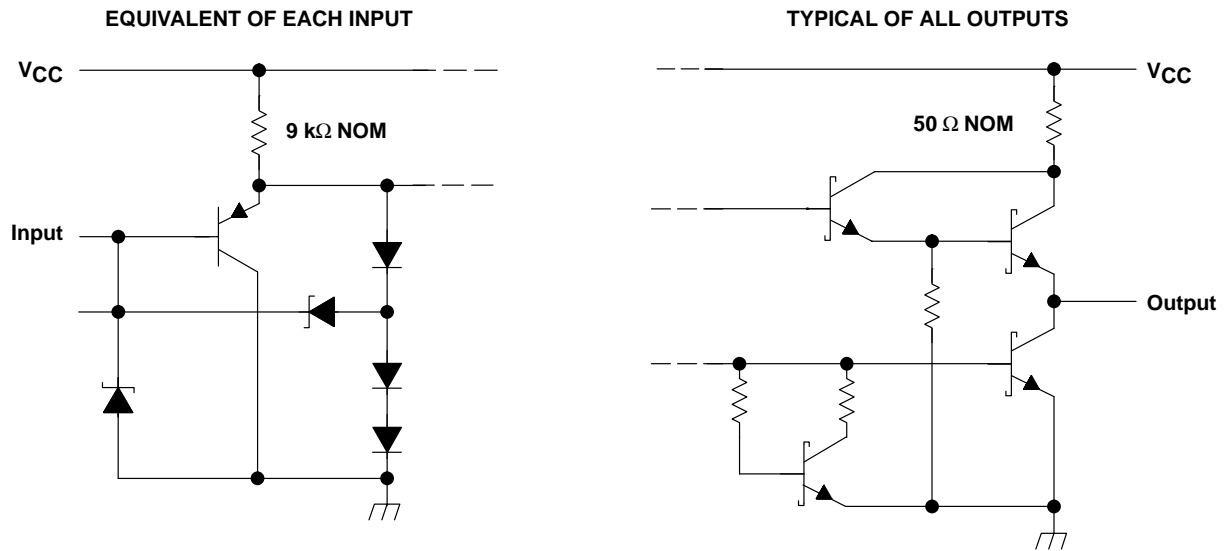
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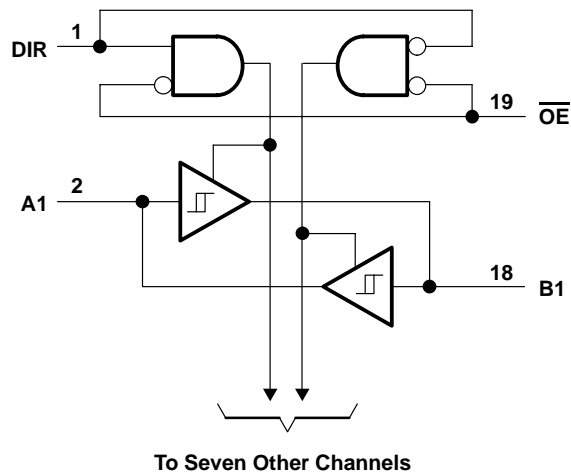
FUNCTION TABLE

INPUTS		OPERATION
\overline{OE}	DIR	
L	L	B data to A bus
L	H	A data to B bus
H	X	Isolation

schematics of inputs and outputs



logic diagram (positive logic)



SN54LS245, SN74LS245 OCTAL BUS TRANSCEIVERS WITH 3-STATE OUTPUTS

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V_{CC}	7 V
Input voltage, V_I (see Note 1)	7 V
Package thermal impedance, θ_{JA} (see Note 2): DB package	70°C/W
DW package	58°C/W
N package	69°C/W
NS package	60°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. All voltage values are with respect to GND.
 2. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions

	SN54LS245			SN74LS245			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC} Supply voltage	4.5	5	5.5	4.75	5	5.25	V
I_{OH} High-level output current			–12			–15	mA
I_{OL} Low-level output current			12			24	mA
T_A Operating free-air temperature	–55		125	0		70	°C



SN54LS245, SN74LS245 OCTAL BUS TRANSCEIVERS WITH 3-STATE OUTPUTS

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITION†	SN54LS245			SN74LS245			UNIT	
			MIN	TYP‡	MAX	MIN	TYP‡	MAX		
V _{IH}	High-level input voltage		2			2			V	
V _{IL}	Low-level input voltage				0.7			0.8	V	
V _{IK}	Input clamp voltage	V _{CC} = MIN, I _I = -18 mA			-1.5			-1.5	V	
Hysteresis (V _{T+} - V _{T-})		A or B V _{CC} = MIN	0.2	0.4		0.2	0.4		V	
V _{OH}	High-level output voltage	V _{CC} = MIN, V _{IH} = 2 V, V _{IL} = V _{IL(max)}	I _{OH} = -3 mA		2.4	3.4	2.4	3.4	V	
			I _{OH} = MAX		2		2			
V _{OL}	Low-level output voltage	V _{CC} = MIN, V _{IH} = 2 V, V _{IL} = V _{IL(max)}	I _{OL} = 12 mA				0.4	0.4	V	
			I _{OL} = 24 mA					0.5		
I _{OZH}	Off-state output current, high-level voltage applied	V _{CC} = MAX, OE at 2 V	V _O = 2.7 V				20	20	μA	
I _{OZL}	Off-state output current, low-level voltage applied	V _{CC} = MAX, OE at 2 V	V _O = 0.4 V				-200	-200	μA	
I _I	Input current at maximum input voltage	A or B DIR or OE	V _{CC} = MAX	V _I = 5.5 V				0.1	0.1	mA
				V _I = 7 V				0.1	0.1	
I _{IH}	High-level input current	V _{CC} = MAX, V _{IH} = 2.7 V			20			20	μA	
I _{IL}	Low-level input current	V _{CC} = MAX, V _{IL} = 0.4 V			-0.2			-0.2	mA	
I _{OS}	Short-circuit output current§	V _{CC} = MAX	-40		-225	40		-225	mA	
I _{CC}	Supply current	Total, outputs high Total, outputs low Outputs at high Z	V _{CC} = MAX	Outputs open		48	70	48	70	mA
						62	90	62	90	
						64	95	64	95	

† For conditions shown as MIN or MAX, use the appropriate values specified under recommended operating conditions.

‡ All typical values are at V_{CC} = 5 V, T_A = 25°C.

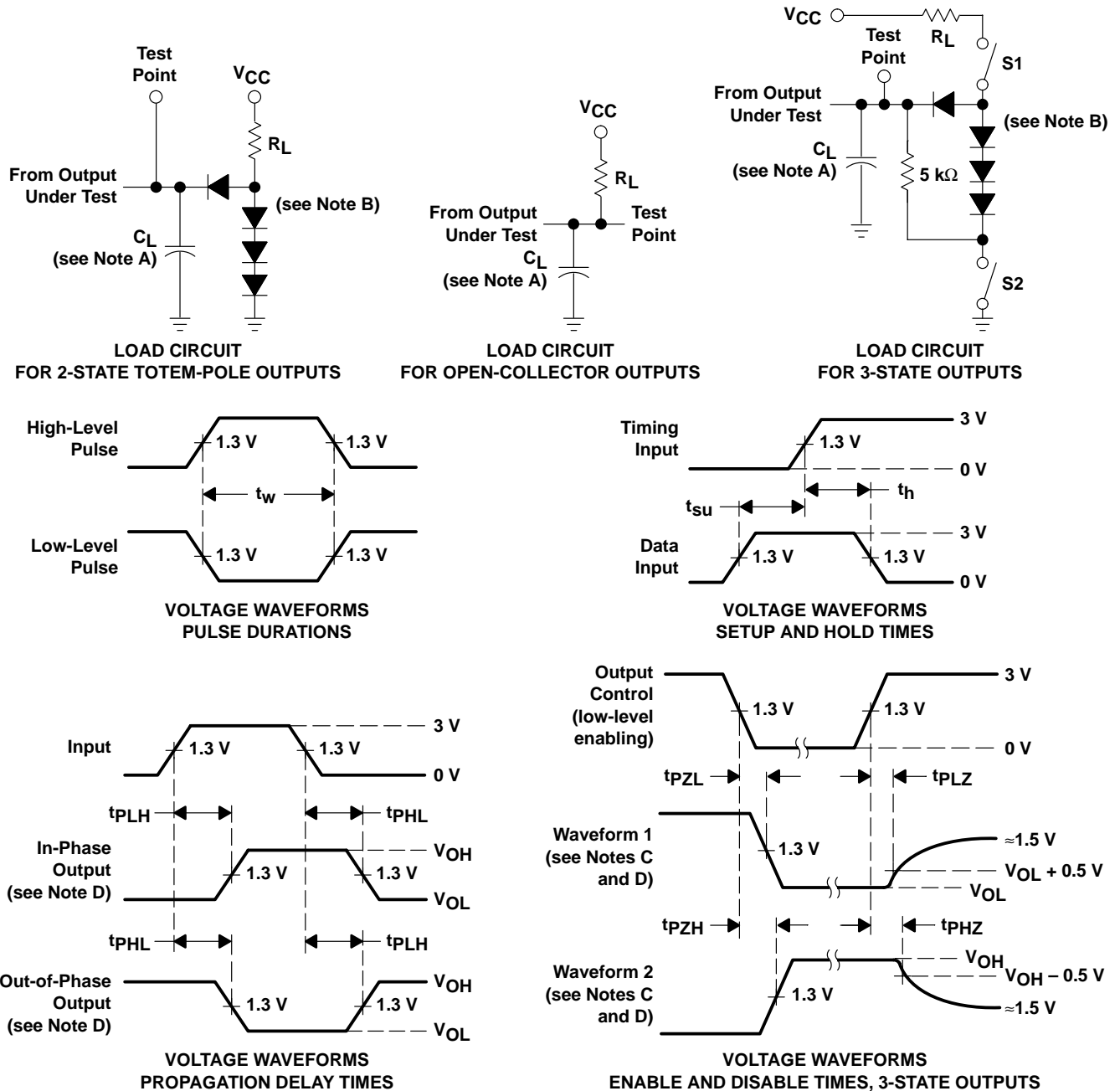
§ Not more than one output should be shorted at a time, and duration of the short circuit should not exceed one second.

switching characteristics, V_{CC} = 5 V, T_A = 25°C (see Figure 1)

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
t _{PLH}	Propagation delay time, low- to high-level output	C _L = 45 pF, R _L = 667 Ω			8	12	ns
t _{PHL}	Propagation delay time, high- to low-level output				8	12	
t _{PZL}	Output enable time to low level	C _L = 45 pF, R _L = 667 Ω			27	40	ns
t _{PZH}	Output enable time to high level				25	40	
t _{PLZ}	Output disable time from low level	C _L = 5 pF, R _L = 667 Ω			15	25	ns
t _{PHZ}	Output disable time from high level				15	28	



PARAMETER MEASUREMENT INFORMATION
SERIES 54LS/74LS DEVICES



- NOTES: A. C_L includes probe and jig capacitance.
 B. All diodes are 1N3064 or equivalent.
 C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 D. S1 and S2 are closed for t_{PLH} , t_{PHL} , t_{PHZ} , and t_{PLZ} ; S1 is open and S2 is closed for t_{pZH} ; S1 is closed and S2 is open for t_{pZL} .
 E. Phase relationships between inputs and outputs have been chosen arbitrarily for these examples.
 F. All input pulses are supplied by generators having the following characteristics: $PRR \leq 1$ MHz, $Z_O \approx 50 \Omega$, $t_r \leq 1.5$ ns, $t_f \leq 2.6$ ns.
 G. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
5962-8002101VRA	ACTIVE	CDIP	J	20	1	TBD	A42 SNPB	N / A for Pkg Type
5962-8002101VSA	ACTIVE	CFP	W	20	1	TBD	A42	N / A for Pkg Type
80021012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
8002101SA	ACTIVE	CFP	W	20	1	TBD	A42	N / A for Pkg Type
JM38510/32803B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
JM38510/32803BRA	ACTIVE	CDIP	J	20	1	TBD	A42 SNPB	N / A for Pkg Type
JM38510/32803BSA	ACTIVE	CFP	W	20	1	TBD	A42	N / A for Pkg Type
SN54LS245J	ACTIVE	CDIP	J	20	1	TBD	A42 SNPB	N / A for Pkg Type
SN74LS245DBR	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS245DBRE4	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS245DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS245DWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS245DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS245DWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS245J	OBSOLETE	CDIP	J	20		TBD	Call TI	Call TI
SN74LS245N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS245N3	OBSOLETE	PDIP	N	20		TBD	Call TI	Call TI
SN74LS245NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS245NSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS245NSRE4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS245NSRG4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SNJ54LS245FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54LS245J	ACTIVE	CDIP	J	20	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54LS245W	ACTIVE	CFP	W	20	1	TBD	A42	N / A for Pkg Type

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered

at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

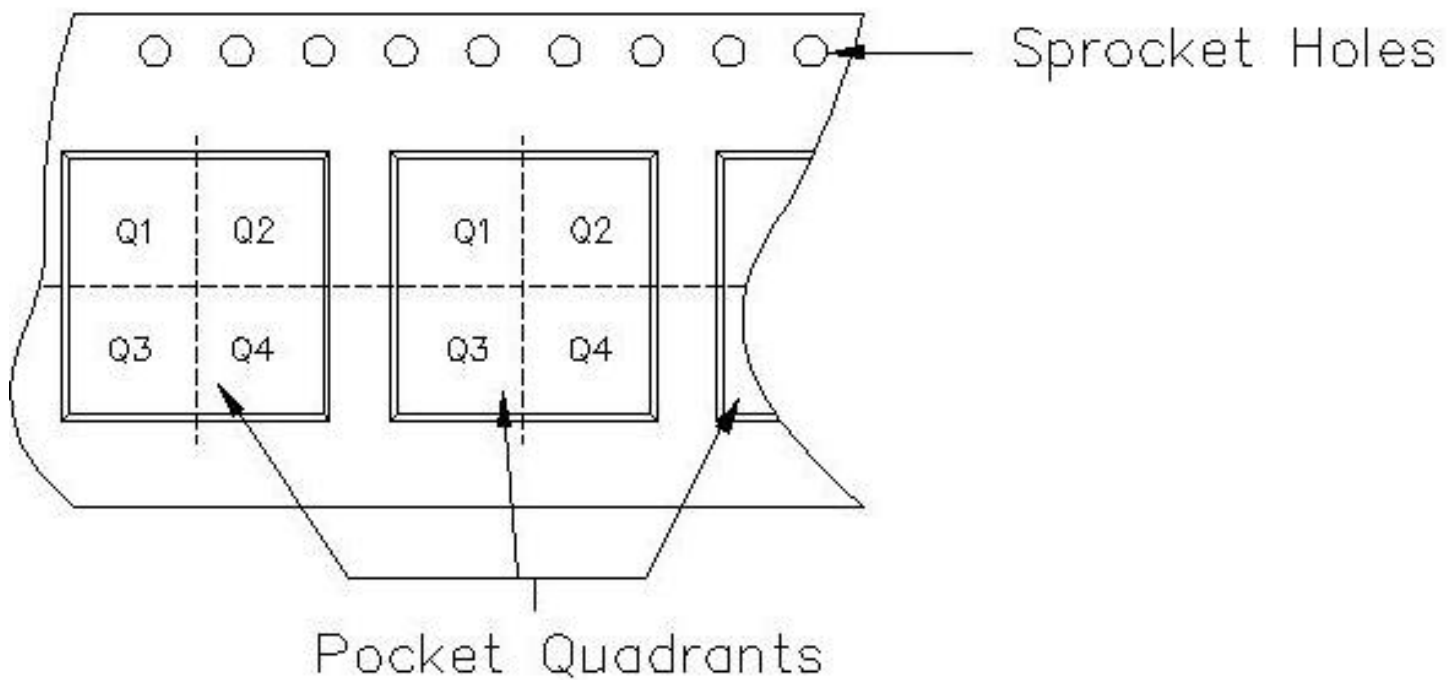
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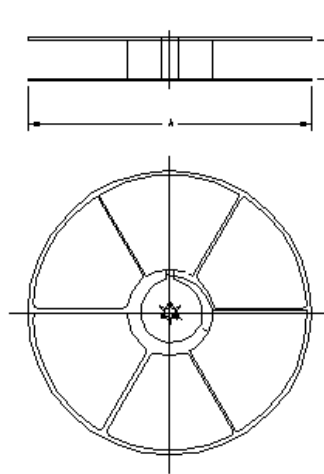
Carrier tape design is defined largely by the component length, width, and thickness.

A_o = Dimension designed to accommodate the component width.
B_o = Dimension designed to accommodate the component length.
K_o = Dimension designed to accommodate the component thickness.
W = Overall width of the carrier tape.
P = Pitch between successive cavity centers.



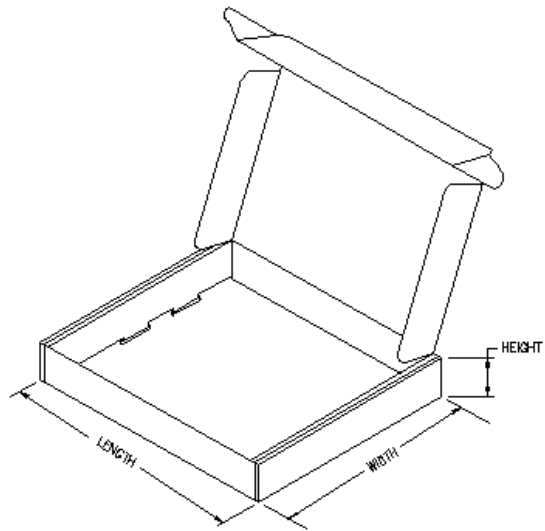
TAPE AND REEL INFORMATION

Device	Package	Pins	Site	Reel Diameter (mm)	Reel Width (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS245DBR	DB	20	MLA	330	16	8.2	7.5	2.5	12	16	Q1
SN74LS245DWR	DW	20	MLA	330	24	10.8	13.0	2.7	12	24	Q1
SN74LS245NSR	NS	20	MLA	330	24	8.2	13.0	2.5	12	24	Q1



TAPE AND REEL BOX INFORMATION

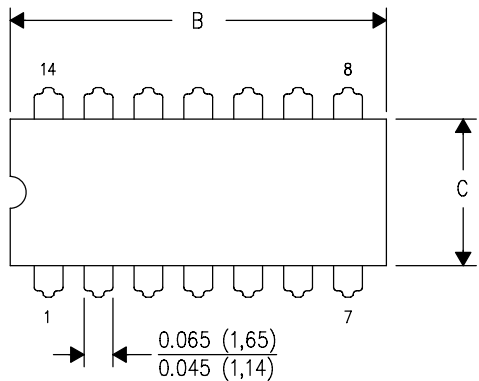
Device	Package	Pins	Site	Length (mm)	Width (mm)	Height (mm)
SN74LS245DBR	DB	20	MLA	333.2	333.2	28.58
SN74LS245DWR	DW	20	MLA	333.2	333.2	31.75
SN74LS245NSR	NS	20	MLA	333.2	333.2	31.75



J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM	PINS **			
	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package is hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F20)

CERAMIC DUAL FLATPACK



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only.
 - E. Falls within Mil-Std 1835 GDFP2-F20

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



4040140/D 10/96

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a metal lid.
 - D. The terminals are gold plated.
 - E. Falls within JEDEC MS-004

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - The 20 pin end lead shoulder width is a vendor option, either half or full width.

DW (R-PDSO-G20)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 - D. Falls within JEDEC MS-013 variation AC.

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-150

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